

**1W High Power 3535 White LED
Technical Data Sheet**

Part No.: DL-PCB3535W100-1W

Double Light

◆ Features:

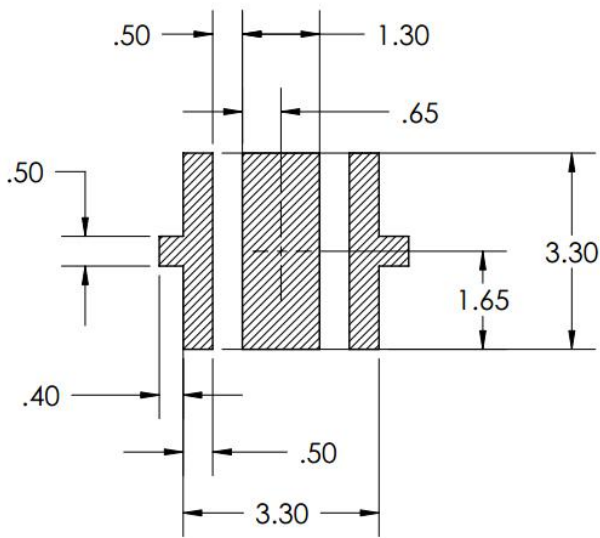
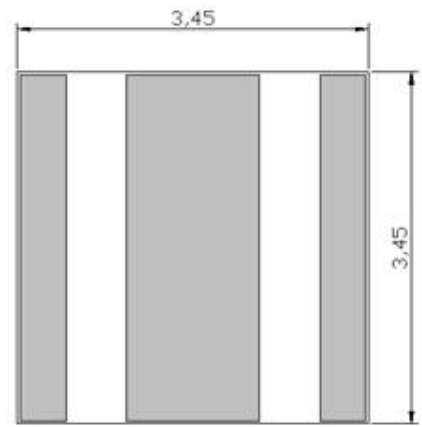
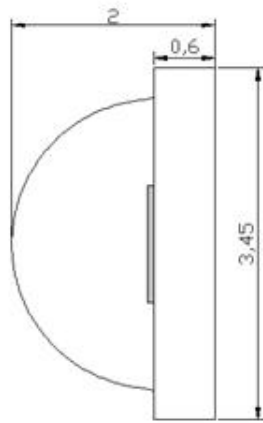
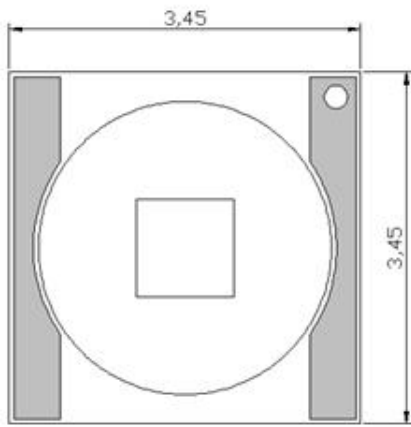
1. Small package with high efficiency
2. Long operating life.
3. Available in white, green, blue, red, yellow, Amber
4. Typical color temperature: 9000-11000 K.
5. View angle: 120°.
6. Low voltage DC operated.
7. The product itself will remain within RoHS compliant Version.
8. ESD protection.

◆ Applications:

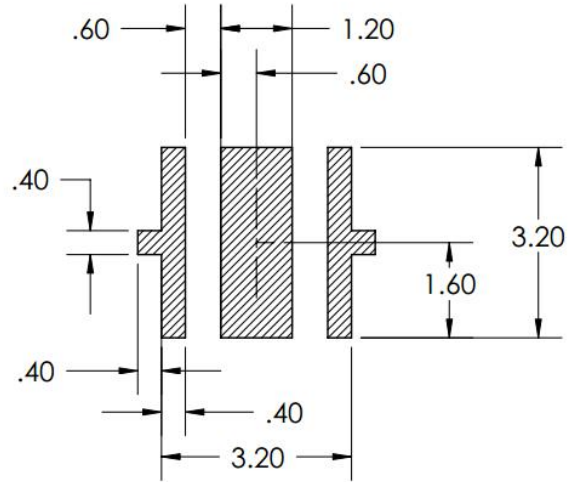
1. Reading lights (car, bus, aircraft).
2. Portable (flashlight, bicycle).
3. Mini accent/Uplighters/Downlighters/Orientation.
4. Bollards/Security/Garden.
5. Cove/Undershelf/Task.
6. Automotive rear combination lamps.
7. Traffic signaling/Beacons/ Rail crossing and Wayside.
8. Indoor/Outdoor Commercial and Residential Architectural.
9. Edge lit signs (Exit, point of sale).
10. LCD Backlights/Light Guides.

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◆ Mechanical Dimensions



建议使用的 PCB 焊盘



建议使用的模板型式
(阴影部分为开口)

Part No.	Chip Material	Lens Color	Source Color
DL-PCB3535W100-1W	InGaN	Yellow Diffused	White

Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.25 mm (.010") unless otherwise noted.
3. Specifications are subject to change without notice.

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◆ Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Max.	Unit
Power Dissipation	PD	1000	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	500	mA
Forward Current	IF	350	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature Range	Topr	-10°C to +70°C	
Storage Temperature Range	Tstg	-20°C to +80°C	
Soldering Temperature	Tsld	260°C for 5 Seconds	

Electrical Optical Characteristics at Ta=25°C

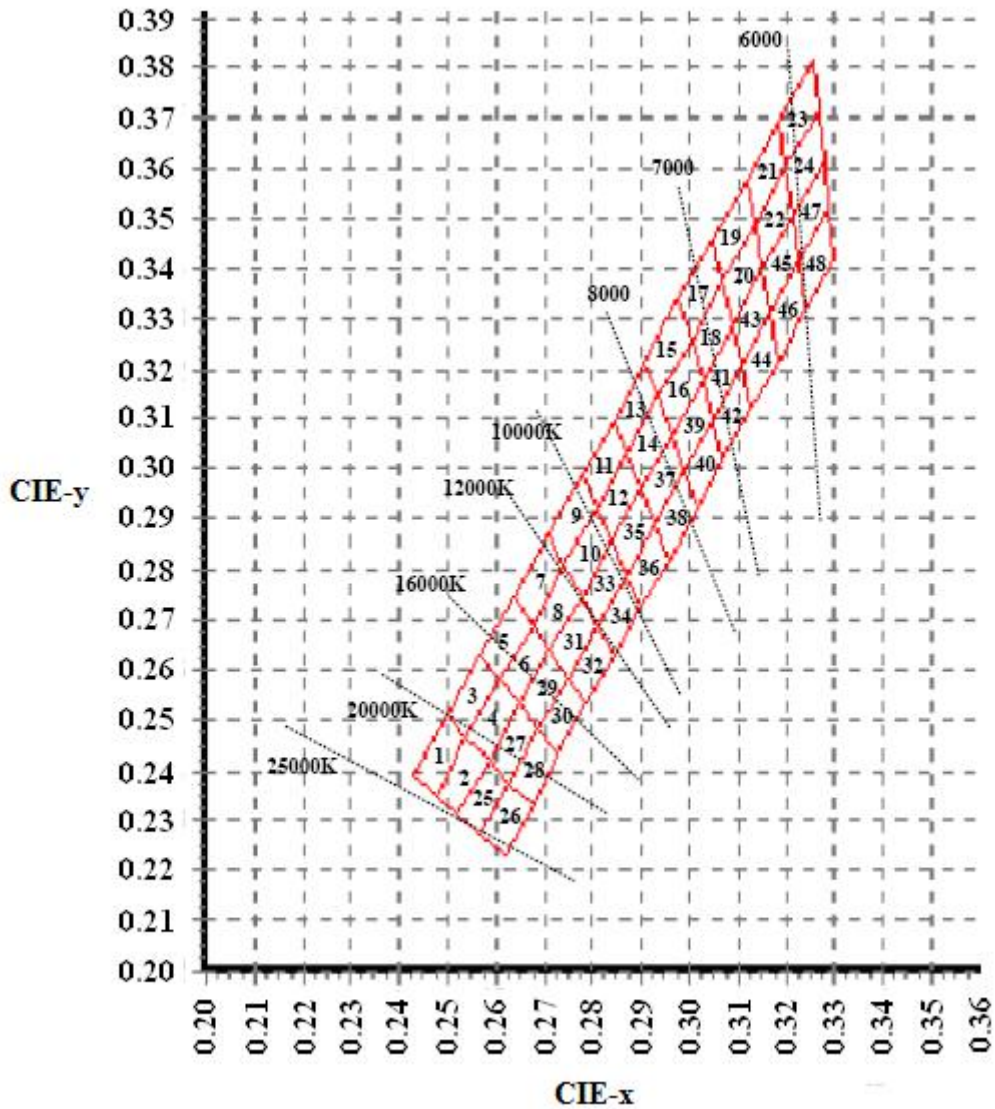
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Flux	Φ	100	120	130	lm	If=350mA (Note 1)
Viewing Angle	$2\theta(1/2)$	---	120	---	Deg	If=350mA
Chromaticity Coordinates	x	---	0.27	---		If=350mA
	y	---	0.28	---		
Color Temperature	TC	9000	---	11000	K	If=350mA
Forward Voltage	VF	2.80	3.40	3.80	V	If=350mA
Reverse Current	IR	---	---	10	μ A	VR=5V

Notes:

1. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

Double Light

◆ CIE Chromaticity Diagram:



Double Light

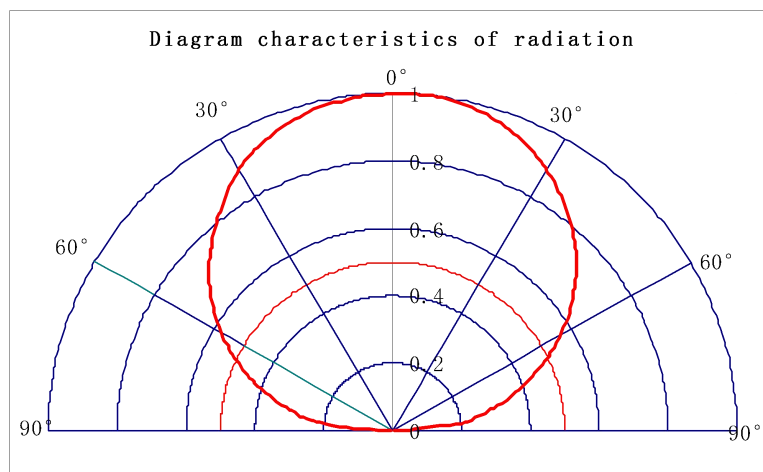
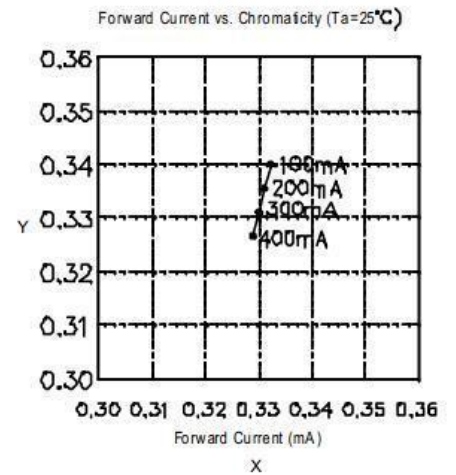
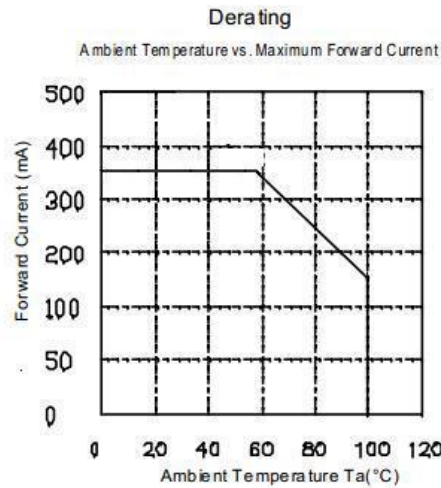
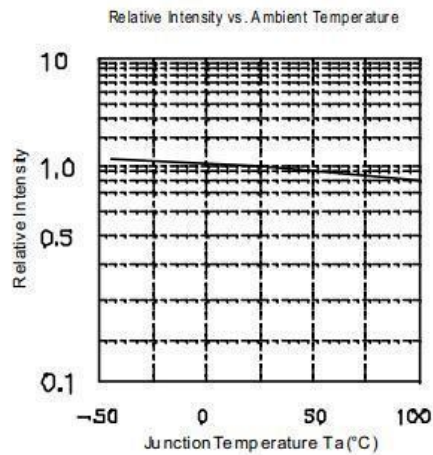
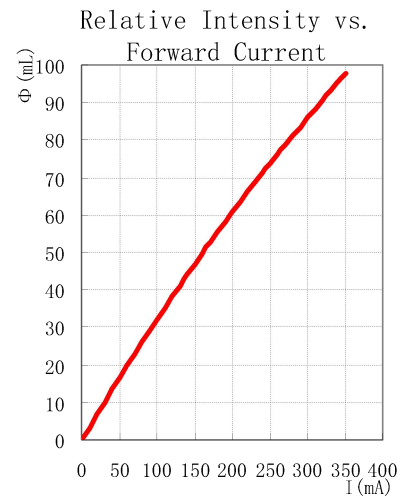
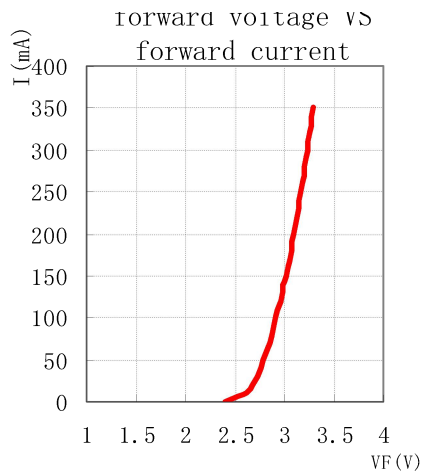
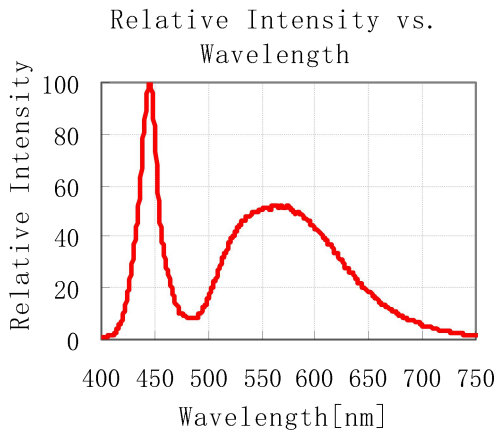
◆ Color Bin Limits

Bin No	Bin code	x	y	Bin No	Bin code	x	y
1	B1	0.249	0.243	25	B3	0.258	0.234
2	B2	0.254	0.239	26	H1	0.263	0.230
3	C5	0.256	0.255	27	C3	0.264	0.245
4	C1	0.260	0.250	28	I1	0.268	0.240
5	C6	0.263	0.266	29	C4	0.270	0.256
6	C2	0.266	0.261	30	I2	0.274	0.251
7	D5	0.269	0.278	31	D3	0.276	0.267
8	D1	0.273	0.272	32	J1	0.280	0.261
9	D6	0.276	0.290	33	D4	0.283	0.277
10	D2	0.279	0.284	34	J2	0.286	0.271
11	E5	0.283	0.302	35	E3	0.289	0.288
12	E1	0.286	0.295	36	K1	0.292	0.281
13	E6	0.289	0.313	37	E4	0.295	0.299
14	E2	0.292	0.306	38	K2	0.298	0.291
15	F5	0.296	0.324	39	F3	0.301	0.309
16	F1	0.299	0.317	40	L1	0.303	0.301
17	F6	0.303	0.339	41	F4	0.307	0.320
18	F2	0.305	0.328	42	L2	0.309	0.311
19	G7	0.310	0.348	43	G4	0.313	0.330
20	G1	0.311	0.339	44	M1	0.315	0.322
21	G8	0.316	0.360	45	G5	0.319	0.341
22	G2	0.318	0.350	46	M2	0.321	0.332
23	G9	0.323	0.371	47	G6	0.326	0.352
24	G3	0.324	0.362	48	M3	0.327	0.342

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◆ Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)



Double Light

◆ Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

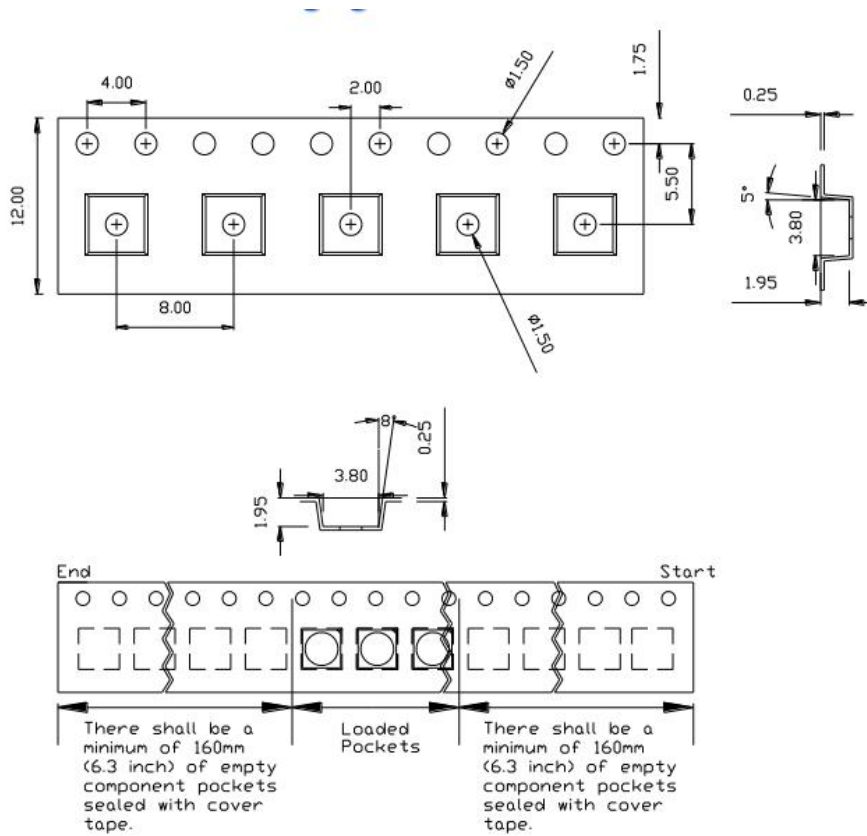
Confidence level: 90%.

LTPD: 10%.

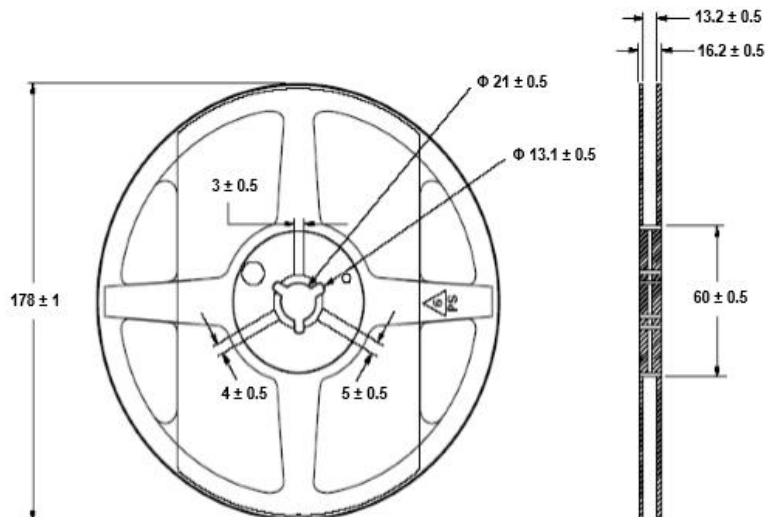
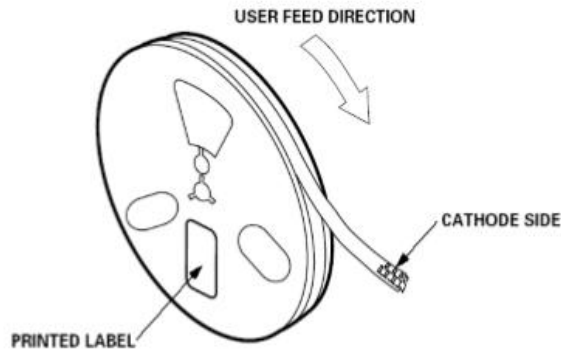
No.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgment Criteria	Ac/ Re
1	Reflow Soldering	TEMP.: 260°C±5°C 5secs	6mins	22pcs	$IR \geq U*2$ $Ee \leq L*0.8$ $VF \geq U*1.2$ U: Upper Specification Limit L: Lower Specification Limit	0/1
2	Temperature Cycle	H: +100°C 15mins ┆ 5 mins ┆ L: -40°C 15mins	50Cycles	22pcs		0/1
3	Thermal Shock	H: +100°C 15mins ┆ 10mins ┆ L: -10°C 5mins	50Cycles	22pcs		0/1
4	High Temperature Storage	TEMP.: +100°C	1000hrs	22pcs		0/1
5	Lower Temperature Storage	TEMP.: -40°C	1000hrs	22pcs		0/1
6	DC Operating Life	V _{CE} =5V	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H.	1000hrs	22pcs		0/1

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◆ Reel Dimensions:



Loaded quantity 1000 per reel.



Double Light

◆ Precautions for Use:

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift may cause enormous current change and burn out failure would happen.

2. Storage

- a) Do not open moisture proof bag before the products are ready to use.
- b) Before opening the package, the Infrareds should be kept at 30°C or less and 90%RH or less.
- c) The Infrared LED should be used within a year.
- d) After opening the package, the Infrareds should be kept at 30°C or less and 70%RH or less.
- e) The Infrared LED should be used within 168 hours (7 days) after opening the package.
- f) If the moisture absorbent material (silicone gel) has faded away or the Infrareds have exceeded the storage time, baking treatment should be performed using the following conditions.
- g) Pre-curing treatment: 60±5°C for 24 hours.

3. Thermal Management

- a) Because the Infrared LED is a high power dissipation device, special and sufficient consideration in thermal management design must be made to optimize the thermal performance.
- b) Heat sink design is implemented in the device for an additional thermal connection. Since the device is capable of SMT process, tin must be spread both heat sink and solder pads areas to dissipate the heat.
- c) A high thermal conductivity substrate, such as Aluminum or Copper plate etc, must be applied for external thermal management. It is strongly recommended that the outer heat sink or PCB dimension per Infrared LED can not be less than 25 x 25 x 1 (L x W x H) mm. The materials for outer heat sink can be FR4 on Aluminum, MCPCB, or FPC on Aluminum.
- d) Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.
- e) Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and Infrared LED lifetime will decrease critically.

4. Soldering Condition

- a) Reflow soldering should not be done more than two times.
- b) While soldering, do not put stress on the Infrareds during heating.
- c) After soldering, do not warp the circuit board.

5. Soldering Iron

- a) For prototype builds or small series production runs it is possible to place and solder the LED by hand.
- b) Dispensing thermal conductive glue or grease on the substrates and follow its curing spec. Press Infrared housing to closely connect Infrared and substrate.
- c) It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.
- d) Be careful because the damage of the product is often started at the time of the hand solder.

6. Handling Indications

- a) During processing, mechanical stress on the surface should be minimized as much as possible.